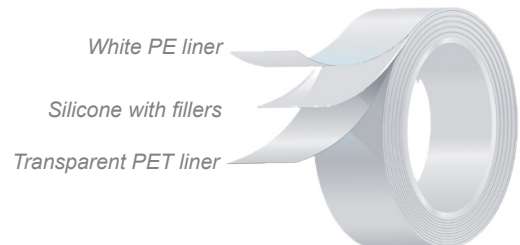


High performance silicone interface for thermal management

Reference: 04 TSI11100 00

Product profile

- Release liner: White PE liner siliconized on one side
- Material: Silicone with fillers
- Release liner: Transparent PET liner siliconized on one side (50 µm)

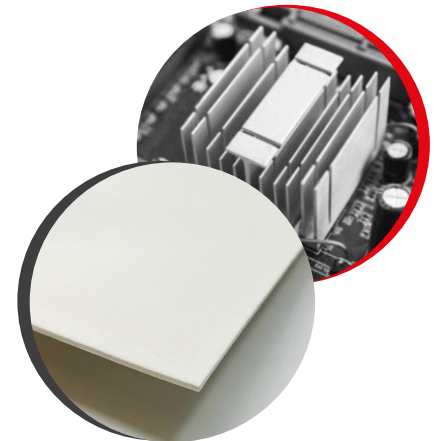


Application

With its unique and highly innovative construction, TSI11-1000 product is designed for the following applications: thermal management, heat-sink thermal interface, LED lighting thermal management.

Technical properties

	Test method	Value
Thickness - without liner (µm)	-	1000
Density	-	1.8
Hardness, Bulk Rubber (Shore 00)	ASTM D2240 at 30s	70
Young modulus (kPa)	ASTM D575	190
Thermal conductivity (W/m.K)	ASTM D5470	1.5
Heat Capacity (J/g.K) (at 20°C)	ASTM E1269	1.3
Electric breakdown voltage (V)	ASTM D 149	AC: 13000 DC: 22000
Volume resistivity (Ω.cm)	ASTM D257	10 ¹¹
Flammability	UL 94	V0
Continuous use temperature (°C)	Internal	-60 to 200



Product features

- European product (technology and manufacturing)
- Silicone oil free (no leakage / low outgazing)
- Wide web process, designed for large volume

Storage

Store in dry conditions between 10 °C and 35 °C in its original packaging.
Use within 12 months after delivery.

Compression ratio	Compression force (N/6,4 cm ²)
10 %	20
20 %	68
30 %	97
40 %	106
50 %	160
Sustain 50 %	35

- Test method: ASTM D575-91 for reference
- Specimen diameter: 28.6 mm
- Platen diameter: 28.6 mm
- Compression velocity: 5 mm /min
- Sustain 50 %: Remaining force after 1min at 50 % compression ratio